Product Change Notice (PCN)

Subject: Add Carsem, Malaysia as Alternate Wafer Test, Final Test and Backend Location
Publication Date: 8/18/2022
Effective Date: 11/17/2022

Revision Description:
Initial Release

Description of Change:
Renesas is adding Carsem, Malaysia as an alternate Wafer Test, Final Test and Backend Location for the select part#. REPG, Malaysia is the current location.

This change will allow flexibility to ship from either facility and will provide the increased capacity, flexibility and shorter lead time to meet market demand. There is no change in the Test and Backend processing flows. Load boards and test programs are the same at both qualified facilities. Renesas has completed the electrical test correlation and based on the test results we do not anticipate any impact on device performance. The testing is fully compatible and transferrable between the test facilities with no change to the test coverage.

Affected Product List: IMX3102-Y1B000NCG, IMX3102-Y1B000NCG8, IMX3112-Y1B000NCG, IMX3112-Y1B000NCG8, IMX3112-Y2B000NCG, IMX3112-Y2B000NCG8.

Reason for Change:
To provide increased capacity.

Impact on Fit, Form, Function, Quality & Reliability:
The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the products.

Product Identification:
Traceability to the Test and Backend location is available on request.

Qualification Status: Electrical characterization completed successfully. Refer Appendix A
Sample Availability Date: 8/18/2022
Device Material Declaration: Not applicable

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.

2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.

3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A – Electrical Characterization Results

Qual Vehicle: IMX3112-Y2B000NCG
Sample size: 1000 electrically good units tested by handler
20 reject units tested by handler

(i)Wafer Test

Descriptions	Existing Wafer Test (REPG, Malaysia)	Alternate Wafer Test (Carsem, Malaysia)
Tester Platform	Advantest V93000	Advantest V93000
Loadboard	DUT_PoppyHills_AW847	DUT_PoppyHills_AW847
Test Program	PHB1_IMX3102_WS PHB2_IMX3112_WS	PHB1_IMX3102_WS PHB2_IMX3112_WS
Test Site	48	48
Test Temperature	85°C	85°C
Test Correlation Results	100%	100%
Number of Good Units	1000 units	1000 units
1000 good units datalog correlation	Passed	Passed
Number of Loop Test	1	1
Number of Reject Units	20 units	20 units
20 reject units datalog correlation	Passed	Passed

(ii)Final Test

Descriptions	Existing Final Test (REPG, Malaysia)	Alternate Final Test (Carsem, Malaysia)
Tester Platform	Advantest V93000	Advantest V93000
Loadboard	DUT_PoppyHills_NCG8	DUT_PoppyHills_NCG8
Test Program	PHB1_IMX3102_FT PHB2_IMX3112_FT	PHB1_IMX3102_FT PHB2_IMX3112_FT
Test Site	16	16
Test Temperature	25°C	25°C
Test Correlation Results	100%	100%

Number of Good Units	1000 units	1000 units
1000 good units datalog correlation	Passed	Passed
Number of Loop Test	1	1
Number of Reject Units	20 units	20 units
20 reject units datalog correlation	Passed	Passed

Descriptions	Existing Backend (REPG, Malaysia)	Alternate Backend (Carsem, Malaysia)
Process Flow	Wafer Sort → Final Test → T&R with inspection → Packing → Shipping	
Pick and Place; Tape and Reel Equipment	Existech 400	Existech 400
AOI	Existech 400	Existech 400
Packing Materials	Same carrier tape & cover tape	
Labeling	Same labeling	

Notes: PNP denotes Pick and Place, TNR denotes Tape and Reel